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D	<div>DESCRIPTION AND REQUIRMENTS FOR FABRICATION OF PRINTED CIRCUIT BOARDS</div> <div>1.GENERAL</div> <div>1.1 General fabrication demands should be according to IPC-6012A, ANSI/IPC-A-600 revision E class 2.</div> <div>The board should be compliance with the European directive for restriction of the use of certain rehazardous substances in Electronic equipment</div> <div>(RoHS directive 2002/95/EC). The board should withstand multiple reflow processes at 260°C Peak temperature</div> <div>2. BOARD DETAILS:</div> <div>2.1 TYPE:() DOUBLE SIDE.</div> <div>MULTILAYER - 4</div> <div>2.2 () SUPPLIED AS PANEL/ () SINGLE.</div> <div>FINAL BOARD THICKNESS: () 0.039 9 () 0.047 () 0.050 () 0.053 (X) 0.062 () 0.093 () 0.125 () 2.3</div> <div>3. MATERIAL:</div> <div>3.1 FINAL copper thickness EXTERNAL: () 1.5OZ (x) 2OZ () 3OZ</div> <div>3.2 FINAL copper thickness INTERNAL: () 0.5OZ () 1OZ (x) 2OZ () 3 OZ</div> <div>3.3 Laminate Materials FR-4 Epoxy resin on woven E-glass base copper clad laminate and prepreg PER IPC-4101-A</div> <div>with High Tg 180C minimum,High thermal decomposition temperature (~300C)</div> <div>CAF resistance, flame resistance UL94 V-0.</div> <div>4. PLATING AND COATING:</div> <div>4.1 SOLDER MASK APPLY TO (X) P.S/C.S (X) CLASS 2 () CLASS 3 PER MIL-55110 () 12 (x) 18 MICRON MIN.</div> <div>4.2 (X) SOLDER MASK (PER IPC-SM-840) CLASS T (X) ON P.S. (X) ON C.S.</div> <div>APPLY COLOR: GREEN</div> <div>4.3 BOARD PLATING: () HASL lead free () OSP=CU-106A-HT (x) IMMERSION GOLD () ELECTROLITIC GOLD.</div> <div>5. MARKING:</div> <div>5.1 LEGEND MARKING SHALL BE ACCORDING TO MASTER ARTWORK WHITE EPOXY INK (X) ON C.S (X) ON P.S.</div> <div>APPLY MARKING TO (X) P.S. (X) C.S.</div> <div>5.2 MANUFACTURE NAME OR SYMBOL AND DATE (WEEK/YEAR) SHALL BE MARK ON THE BOARD:</div> <div>(X) IN A CONDUCTOR AND LEGEND FREE AREA</div> <div>() LOCATION SHOWN ON DRAWING.</div> <div>5.3 UL RECOGNITION AND FLAMMABILITY RATING SHALL APPEAR NEAR THE MANUFACTURER'S.</div> <div>5.4 FLAMIBILITY RATING (94V-0 MIN)</div> <div>5.5 TEMP RATING: (X) 105C MIN () 130C MIN</div> <div>6. DIMENSION TOLERANCE:+/-</div> <div>HOLE LOCATION :0.003" (0.075mm).</div> <div>CONDUCTOR WIDTH : 0.002" (0.05mm).</div> <div>HOLE DIAMETER; NON PLATED:0.002"(0.05mm) PLATED:0.003" (0.075mm).</div> <div>OUTLINE DIMENSION : 0.005" (0.125mm).</div> <div>BOARD FLATNESS: 0.01" PER 1".</div> <div>DRILL TOLERANCE: 0.002"(0.05mm).</div> <div>7. CONDUCTOR DEFINIYION:</div> <div>7.1 CIRCUITRY PATTERNS ACCORDING TO ARTWORK SUPPLIED BY THE COSTOMER.</div> <div>7,2 MINIMUM ANNULAR RING EXTERNAL - 0.050mm.</div> <div>7.3 MINIMUM ANNULAR RING INTERNAL - 0.025mm.</div> <div>8. PACKING & SHIPMENT:</div> <div>NO MORE THEN 20 PCB'S IN EACH SEALED ANTISTATIC BAG.</div> <div>EACH BOARD SHOULD BE SEPARATED BY A LEAF OF PAPER.</div> <div>9. TEST COUPON:ONE PRODUCTION BOARD/ON ARTWORK/TO BE SUPPLIED BY THE VENDOR.</div> <div>10. FILES: MANUFACTURE ACCORDING GERBER FILES ONLY,DO NOT CHECK IPC FILE.</div> <div>11. Default Tg- 180</div>				D
C					C
B					B
A	<div>UNLESS OTHERWISE SPECIFIED</div> <div>ALL DIMENSIONS ARE IN MM.</div> <div>DO NOT SCALE DRAWING</div> <div>DRAWN</div> <div>OLGA M.</div> <div>20.08.18</div> <div>LINEAR ± - MM</div> <div>HOLE DIA. + - MM</div> <div>ANGULAR ± - °</div> <div>DRAFTANGLE/SIDE - °Max.</div> <div>BURR & FLASH - Max.</div> <div>DESIGN</div> <div>LAZAR R.</div> <div>CHEKED</div> <div>MARKI S.</div> <div>PROJECT</div> <div>MANAGER</div> <div>BREAK SHARP CORNERS & SHARP EDGES</div> <div>SCALE</div> <div>NONE</div> <div>SHEET</div> <div>2 OF 2</div> <div>A4</div> <div>TITLE</div> <div>PCB 25W High Density PD Flyback Conv</div> <div>PART NUMBER</div> <div>PR-1491-B00</div> <div>DWG.REV.</div> <div>00</div> <div>PART.REV.</div> <div>B00</div>				A
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